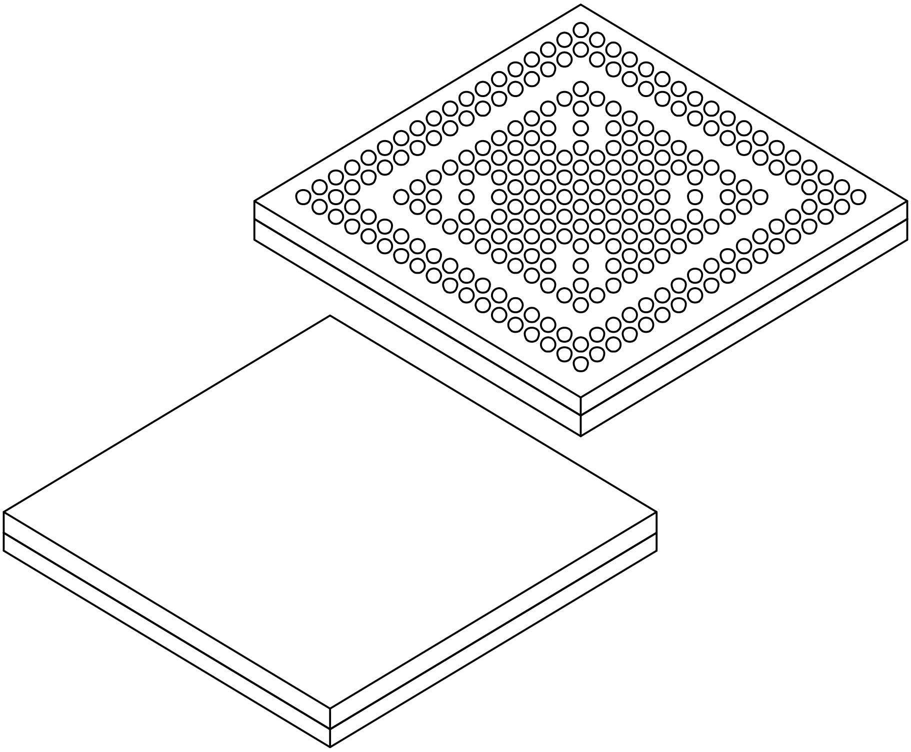
256-Ball Thin Fine Pitch Ball Grid Array (AYB) - 8x8x1.05 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	256		
Pitch	e	0.40 BSC		
Overall Height	A	-	-	1.05
Ball Height	A1	0.11	0.16	0.21
Substrate Thickness	S	0.26 REF		
Mold Cap Thickness	M	0.45 REF		
Overall Length	D	8.00 BSC		
Overall Pitch	eD	6.80 BSC		
Overall Width	E	8.00 BSC		
Overall Pitch	eE	6.80 BSC		
Ball Diameter	b	0.20	0.25	0.30

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-21133 Rev A Sheet 2 of 2